

FORM PTO-1449 (Modified)		U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: COOL-01600		Serial No.: 10/643,684	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Thomas W. Kenny et al.			
(37 CFR 1.128(b))				Filing Date: August 18, 2003		Group Art Unit: 1763	
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS							
	Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
						Yes	No
	97212126.9	03/04/97	CN	BO1D	61/42		X
AB	2000-277540	10/06/00	JP	H01L	21/50		X
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)							
AC	Stephen C. Jacobson et al., "Fused Quartz Substrates for Microchip Electrophoresis", Analytical Chemistry, Vo. 67, No. 13, July 1, 1995, pages 2059-2063.						
AD	Kendra V. Sharp et al., "Liquid Flows in Microchannels", 2002, Vol. 6, pages 6-1 to 6-38.						
AE	Shuchi Shoji et al., "Microflow devices and systems", J. Microtech. Microeng. 4 (1994), pages 157-171, printed in the U.K.						
AF	Angela Rasmussen et al., "Fabrication Techniques to Realize CMOS-Compatible Microfluidic Microchannels", Journal of Microelectromechanical, Vo. 10, No. 2, June 2001, pages 286-297.						
AG	J. H. Wang et al., "Thermal-Hydraulic Characteristic of Micro Heat Exchangers", 1991, DSC-Vol. 32, Micromechanical Sensors, Actuators, and Systems, pages 331-339.						
AH	Gad Hetsroni et al., "Nonuniform Temperature Distribution in Electronic Devices Cooled by Flow in Parallel Microchannels", IEEE Transactions on Components and Packaging Technologies, March 2001, Vol. 24, No. 1, pages 16-23.						
AI	X. F. Peng et al., "Heat Transfer Characteristics of Water Flowing through Microchannels", Experimental Heat Transfer An International Journal, Vol. 7, No. 4, October-December 1994, pages 265-283.						
AJ	Linan Jiang et al., "Forced Convection Boiling in a Microchannel Heat Sink", Journal of Microelectromechanical Systems, Vol. 10, No. 1, March 2001, pages 80-87.						
AK	Muhammad M. Rahman et al., "Experimental Measurements of Fluid Flow and Heat Transfer in Microchannel Cooling Passages in a Chip Substrate", 1993, EEP-Vol. 4-2, Advances in Electronic Packages, pages 685-692.						
AL	X. F. Peng et al., "Forced convection and flow boiling heat transfer for liquid flowing through Microchannels", 1993, Int. J. Heat Mass Transfer, Vol. 36, No. 14, pages 3421-3427.						
AM	Lung-Jieh Yang et al., "A Micro Fluidic System of Micro Channels with On-Site Sensors by Silicon Bulk Micromachining", September 1999, Microfluidic Devices and Systems II, Vol. 3877, pages 267-272.						
AN	G. Mohiuddin Mala et al., "Heat transfer and fluid flow in microchannels", 1997, Int. J. Mass transfer, Vol. 40, No. 13, pages 3079-3088, printed in Great Britain.						
AO	J. M. Cuta et al., "Fabrication and Testing of Micro-Channel Heat Exchangers", SPIE Microlithography and Metrology in Micromachining, Vol. 2640, 1995, pages 152-160.						
AP	Linan Jiang et al., "A Micro-Channel Heat Sink with Integrated Temperature Sensors for Phase Transition Study", 1999, 12 th IEEE International Conference on Micro Electro Mechanical Systems, pages 159-164.						
AQ	Linan Jiang et al., "Fabrication and characterization of a microsystem for a micro-scale heat transfer study", J. Micromech. Microeng. 9 (1999) pages 422-428, printed in the U.K.						
AR	M. B. Bowers et al., "High flux boiling in low flow rate, low pressure drop mini-channel and micro-channel heat sinks", 1994, Int. J. Heat Mass Transfer, Vol. 37, No. 2, pages 321-332.						
AS	Yongendra Joshi, "Heat out of small packages", December 2001, Mechanical Engineer, pages 56-58.						
AT	A. Rostami et al., "Liquid Flow and Heat Transfer in Microchannels: a Review", 2000, Heat and Technology, Vol. 18, No. 2, pages 59-68.						
AU	Lian Zhang et al., "Measurements and Modeling of Two-Phase Flow in Microchannels with Nearly Constant Heat Flux Boundary Conditions", Journal of Microelectromechanical Systems, Vol. 11, No. 1, February 2002, pages 12-19.						
AV	Muhammad Mustafizur Rahman, "Measurements of Heat Transfer in Microchannel Heat Sinks", Int. Comm. Heat Mass Transfer, Vol. 27, No. 4, May 2000, pages 495-506.						
AW	Issam Mudawar et al., "Enhancement of Critical Heat Flux from High Power Microelectronic Heat Sources in a Flow Channel", Journal of Electronic Packaging, September 1990, Vol. 112, pages 241-248.						
AX	Nelson Kuan, "Experimental Evaluation of Micro Heat Exchangers Fabricated in Silicon", 1996, HTD-Vol. 331, National Heat Transfer Conference, Vol. 9, pages 131-136.						
AY	E. W. Kreutz et al., "Simulation of micro-channel heat sinks for optoelectronic microsystems", Microelectronics Journal 31(2000) pages 787-790.						
AZ	J. C. Y. Koh et al., "Heat Transfer of Microstructure for Integrated Circuits", 1986, Int. Comm. Heat Mass Transfer, Vol. 13, pages 89-98.						
BA	Szezana Konecni et al., "Convection Cooling of Microelectronic Chips", 1992, InterSociety Conference on Thermal Phenomena, pages 138-144.						
Examiner: <i>McM</i>				Date Considered: <i>8-2-04</i>			
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OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)					
JM	BB	Michael B. Kleiner et al., "High Performance Forced Air Cooling Scheme Employing Microchannel Heat Exchangers", 1995, IEEE Transactions on Components, Packaging, and Manufacturing Technology-Part A, Vol. 18, No. 4, pages 795-804.			
	BC	Jerry K. Keska Ph. D. et al., "An Experimental Study on an Enhanced Microchannel Heat Sink for Microelectronics Applications", EEP-Vol. 26-2, Advances in Electronic Packaging, 1999, Vol. 2, pages 1235-1259.			
	BD	Shung-Wen Kang et al., "The Performance Test and Analysis of Silicon-Based Microchannel Heat Sink", July 1999, Terahertz and Gigahertz Photonics, Vol. 3795, pages 259-270.			
	BE	Joseph C. Tramontana, "Semiconductor Laser Body Heat Sink", Xerox Disclosure Journal, Vol. 10, No. 6, November/December 1985, pages 379-381.			
	BF	Sarah Arulananandam et al., "Liquid transport in rectangular microchannels by electroosmotic pumping", Colloid and Surfaces A: Physicochemical and Engineering Aspects 161 (2000), pages 89-102.			
	BG	Jeffery D. Barner et al., "Thermal Ink Jet Print Head Carriage with Integral Liquid Cooling Capabilities", Xerox Disclosure Journal-Vol. 21, No. 1, January/February 1996, pages 33-34.			
	BH	"Autonomous displacement of a solution in a microchannel by another solution", Research Disclosure, June 2001, pages 1046-1047.			
	BI	John M. Waldvogel, "Aluminum Silicon Carbide Phase Change Heat Spreader", Motorola, June 1999, Technical Developments, pages 226-230.			
	BJ	James P. Slupe et al., "An idea for maintaining a stable thermal environment for electronic devices", Research Disclosure, August 2001, page 1312.			
	BK	John M. Waldvogel, "A Heat Transfer Enhancement Method for Forced Convection Bonded-Fin Heatsinks", Motorola, December 1997, Technical Developments, pages 158-159.			
	BL	"Thin Heat Pipe for Cooling Components on Printed Circuit Boards", IBM Technical Disclosure Bulletin, Vol. 34, No. 7B, December 1991, pages 321-322.			
	BM	R. C. Chu et al., "Process for Nucleate Boiling Enhancement", IBM Technical Disclosure Bulletin, Vol. 18, No. 7, December 1975, page 2227.			
	BN	J. Riseman, "Structure for Cooling by Nucleate Boiling", IBM Technical Disclosure Bulletin, Vol. 18, No. 11, April 1976, page 3700.			
	BO	"Integrally Grooved Semiconductor Chip and Heat Sink", October 1971, IBM Technical Disclosure Bulletin, Vol. 14, No. 5, page 1425.			
	BP	"Enhanced Cooling of Thermal Conduction Module", IBM Technical Disclosure Bulletin, Vol. 30, No. 5, October 1987, page 426.			
	BQ	"Heat Exchanger Modules for Data Process with Valves Operated by Pressure form Cooling Water Pump", IBM Technical Disclosure Bulletin, Vol. 30, No. 5, October 1987, page 419.			
	BR	"Cold Plate for Thermal Conduction Module with Inlet for Cooling Water Near Highest Power Chips", IBM Technical Disclosure Bulletin, Vol. 30, No. 5, October 1987, page 413.			
	BS	"Circuit Module Cooling with Coaxial Bellow Providing Inlet, Outlet and Redundant Connections to Water-Cooled Element", IBM Technical Bulletin, Vol. 30, No. 5, October 1987, pages 345-347.			
	BT	"Piping System with Valves Controlled by Processor for Heating Circuit Modules in a Selected Temperature Profile for Sealing Integrity Test Under Temperature Stress", IBM Technical Disclosure Bulletin, Vol. 30, No. 5, October 1987, page 336.			
	BU	"Cooling System for Chip Carrier on Card", IBM Technical Disclosure Bulletin, Vol. 31, No. 4, September 1988, pages 39-40.			
	BV	"Chip Cooling Device", IBM Technical Disclosure Bulletin, Vol. 30, No. 9, February 1988, pages 435-436.			
	BW	W. E. Ahearn et al., "Silicon Heat Sink Method to Control Integrated Circuit Chip Operating Temperatures", IBM Technical Disclosure Bulletin, Vol. 21, No. 8, January 1979, pages 3378-3380.			
	BX	N. P. Bailey et al., "Cooling Device for Controlled Rectifier", IBM Technical Disclosure Bulletin, Vol. 21, No. 11, April 1979, pages 4609-4610.			
	BY	W. J. Kleinfelder et al., "Liquid-Filled Bellows Heat Sink", IBM Technical Disclosure Bulletin, Vol. 21, No. 10, March 1979, pages 4125-4126.			
	BZ	R. P. Chrisfield et al., "Distributed Power/Thermal Control", IBM Technical Disclosure Bulletin, Vol. 22, No. 3, August 1979, pages 1131-1132.			
	CA	A. J. Arnold et al., "Heat Sink Design for Cooling Modules in a Forced Air Environment", IBM Technical Disclosure Bulletin, Vol. 22, No. 6, November 1979, pages 2297-2298.			
	CB	A. J. Arnold, "Structure for the Removal of Heat from an Integrated Circuit Module", IBM Technical Disclosure Bulletin, Vol. 22, No. 6, November 1979, pages 2294-2296.			
	CC	U. P. Hwang et al., "Cold Plate for Thermal Conduction Module with Improved Flow Pattern and Flexible Base", IBM Technical Disclosure Bulletin, Vol. 25, No. 9, February 1983, page 4517.			
JM	CD	K. C. Gallagher et al., "Cooling System for Data Processor with Flow Restrictor in Secondary Loop to Limit Bypass-Cooling Water Flow", IBM Technical Disclosure Bulletin, Vol. 26, No. 5, October 1983, page 2658.			
Examiner: <i>Paul M.</i>				Date Considered: <i>8-2-04</i>	
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TM	CE	R. C. Chu et al., "Silicon Heat Sink for Semiconductor Chip", IBM Technical Disclosure Bulletin, Vol. 24, No. 11A, April 1982, page 5743.					
	CF	J. M. Eldridge et al., "Heat-Pipe Vapor Cooling Etched Silicon Structure", IBM Technical Disclosure Bulletin, Vol. 25, No. 8, January 1983, pages 4118-4119.					
	CG	J. R. Skobern, "Thermoelectrically Cooled Module", IBM Technical Disclosure Bulletin, Vol. 27, No. 1A, June 1984, page 30.					
	CH	M. J. Brady et al., "Etched Silicon Integrated Circuit Heat Sink", IBM Technical Disclosure Bulletin, Vol. 27, No. 1B, June 1984, page 627.					
	CI	H. D. Edmonds et al., "Heat Exchange Element for Semiconductor Device Cooling", IBM Technical Disclosure Bulletin, Vol. 23, No. 3, August 1980, page 1057.					
	CJ	R. W. Noth, "Heat Transfer from Silicon Chips and Wafers", IBM Technical Disclosure Bulletin, Vol. 17, No. 12, May 1975, page 3544.					
	CK	"Forced Boiling Cooling System with Jet Enhancement for Critical Heat Flux Extension", IBM Technical Disclosure Bulletin, Vol. 39, No. 10, October 1996, page 143.					
	CL	"Miniature Heat Exchanger for Corrosive Media", IBM Technical Disclosure Bulletin, Vol. 38, No. 01, January 1995, pages 55-56.					
	CM	"Self-Contained Active Heat Dissipation Device", IBM Technical Disclosure Bulletin Vol. 39, No. 04, April 1996, pages 115-116.					
	CN	C. J. Keller et al., "Jet Cooling Cup for Cooling Semiconductor Devices", IBM Technical Disclosure Bulletin, Vol. 20, No. 9, February 1978, pages 3575-3576.					
	CO	B. J. Ronkese, "Centerless Ceramic Package with Directly Connected Heat Sink", IBM Technical Disclosure Bulletin, Vol. 20, No. 9, February 1978, page 3577-3578.					
	CP	K. S. Sachar, "Liquid Jet Cooling of Integrated Circuit Chips", Vol. 20, No. 9, February 1978, pages 3727-3728.					
	CQ	A. H. Johnson, "Device Cooling", IBM Technical Disclosure Bulletin, Vol. 20, No. 10, March 1978, pages 3919-3920.					
	CR	A. L. Pacuzzo et al., "Integrated Circuit Module Package Cooling Structure", IBM Technical Disclosure Bulletin, Vol. 20, No. 10, March 1978, pages 3898-3899.					
	CS	R. D. Durand et al., "Flexible Thermal Conductor for Electronic Module", IBM Technical Disclosure Bulletin, Vol. 20, No. 11A, April 1978, page 4343.					
	CT	D. Balderes et al., "Liquid Cooling of a Multichip Module Package", IBM Technical Disclosure Bulletin, Vol. 20, No. 11A, April 1978, pages 4336-4337.					
	CU	J. A. Dorler et al., "Temperature Triggerable Fluid Coupling System for cooling Semiconductor Dies", IBM Technical Disclosure Bulletin, Vol. 20, No. 11A, April 1978, pages 4386-4388.					
	CV	V. W. Antonetti et al., "Integrated Module Heat Exchanger", IBM Technical Disclosure Bulletin, Vol. 20, No. 11A, April 1978, page 4498.					
	CW	P. Hwang et al., "Conduction Cooling Module", IBM Technical Disclosure Bulletin, Vol. 20, No. 11A, April 1978, pages 4334-4335.					
	CX	A. J. Arnold, "Electronic Packaging Structure", IBM Technical Disclosure Bulletin, Vol. 20, No. 11B, April 1978, pages 4820-4822.					
CY	V. Y. Doo et al., "High Performance Package for Memory", IBM Technical Disclosure Bulletin, Vol. 21, No. 2, July 1978, pages 585-586.						
CZ	"Multi-Chip Package with Cooling by a Spreader Plate in Contact with a Chip having Cylindrical Holes Mating with an Inverse Frame Providing Water Flow Within its Pins", IBM Technical Disclosure Bulletin, Vol. 31, No. 5, October 1988, pages 141-142.						
DA	J. Landrock et al., "Cooling System for Semiconductor Chips", IBM Technical Disclosure Bulletin, Vol. 23, No. 4, September 1980, page 1483.						
DB	E. P. Damm, Jr., "Convection Cooling Apparatus", IBM Technical Disclosure Bulletin, Vol. 20, No. 7, December 1977, pages 2755-2756.						
DC	"Circuit Package with Circulating Boiling Liquid and Local Heat Exchanger to Limit Vapor in Coolant Outlet", IBM Technical Disclosure Bulletin, Vol. 31, No. 12 May 1989, page 34.						
DD	"Circuit Module Cooling with Multiple Pistons Contacting a Heat Spreader/Electrical Buffer Plate in Contact with Chip", IBM Technical Disclosure Bulletin, Vol. 31, No. 12, May 1989, page 5-7.						
DE	"TCM-LIKE Circuit Module with Local Heat Sink Resting on Chip and Chip Separated From Coolant by Bellows with Pins and Deflector Plate Attached to Local Heat Sink and Extending Above Bellows into Region of Coolant Flow", IBM Technical Disclosure Bulletin, Vol. 31, No. 11, pages 305-306.						
DF	"Water-Cooled Circuit Module with Grooves Forming Water Passages Near Heat-Producing Devices", IBM Technical Disclosure Bulletin, Vol. 31, No. 12, May 1989, pages 49-50.						
TM	DG	"Cold Plate for Thermal conduction Module with Only Peripheral Mounting bolts, Large Surface Area Fin Inserts and Reduced Water Flow and Thermal Resistances", IBM Technical Disclosure Bulletin, Vol. 31, No. 12, May 1989, page 59.					
Examiner: <i>Thell M. G.</i>				Date Considered: <i>8-2-04</i>			
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OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

TM	DH	"Thermal Control Hardware for Accelerated Run-In Testing of Multi-Chip Modules", IBM Technical Disclosure Bulletin, Vol. 32, No. 5A, October 1989, page 129-130.
	DI	"Means of Removing More Heat From a TCM (Or Other Liquid-Cooled Logic Package) By Reducing the Coolant Temperature", IBM Technical Disclosure Bulletin, Vol. 32 No. 5A, Oct 1989, pages 153-154.
	DJ	E. G. Loeffel et al., "Liquid Cooled Module with Compliant Membrane", IBM Technical Disclosure Bulletin, Vol. 20, No. 2, July 1977, pages 673-674.
	DK	V. Y. Doo et al., "Method of Effective Cooling of a High Power Silicon Chip", IBM Technical Disclosure Bulletin, Vol. 20, No. 4, September 1977, page 1436-1437.
	DL	V. Y. Doo et al., "Semiconductor Chip Cooling Package, IBM Technical Disclosure Bulletin, Vol. 20, No. 4, September 1977, pages 1440-1441.
	DM	"Heat Sink Fabrication Method", IBM Technical Disclosure Bulletin, Vol. 27, No. 10A, March 1985, page 5656-5657.
	DN	"Thermal Conduction Module with Liquid Dielectric and Pistons with Surface Treatment for Enhanced Nucleate Boiling", IBM Technical Disclosure Bulletin, Vol. 27, No. 12, May 1985, page 6904.
	DO	"Pin Fin Array Heat Pipe Apparatus", IBM Technical Disclosure Bulletin, Vol. 37, No. 09, September 1994, page 171.
	DP	Youngcheol Joo et al., "Fabrication of Monolithic Microchannels for IC Chip Cooling", 1995, IEEE Micro Electro Mechanical Systems, pages 362-367.
	DQ	Jaisree Moorthy et al., <u>Active control of electroosmotic flow in microchannels using light</u> , January 26, 2001, Sensors and Actuators B 75, pages 223-229.
	DR	Andreas Manz et al., <u>Electroosmotic pumping and electrophoretic separations for miniaturized chemical analysis systems</u> , September 16, 1994, J. Micromech. Microeng. 4 (1994), pages 257-265, printed in the U.K.
	DS	E. B. Cummings et al., <u>Irrationality of uniform electroosmosis</u> , September 1999, Part of the SPIE Conference on Microfluidic Devices and Systems II, SPIE Vol. 3877, pages 180-189.
	DT	Stephen C. Jacobson et al., <u>Fused Quartz Substrates for Microchip Electrophoresis</u> , July 1, 1995, Analytical Chemistry, Vol. 67, No. 13, pages 2059-2063.
	DU	Haim H. Bau, <u>Optimization of conduits' shape in micro heat exchangers</u> , December 10, 1997, International Journal of Heat and Mass Transfer 41 (1998), pages 2717-2723.
	DV	V. K. Dwivedi et al., <u>Fabrication of very smooth walls and bottoms of silicon microchannels for heat dissipation of semiconductor devices</u> , January 25, 2000, Microelectronics Journal 31 (2000), pages 405-410.
	DW	M. B. Bowers et al., <u>Two-Phase Electronic Cooling Using Mini-Channel and Micro-Channel Heat Sinks: Part 2-Flow Rate and Pressure Drop Constraints</u> , December 1994, Journal of Electronic Packaging 116, pages 298-305.
	DX	Meint J. de Boer et al., <u>Micromachining of Buried Micro Channels in Silicon</u> , March 2000, Journal of Microelectromechanical systems, Vol. 9, No. 1, pages 94-103.
	DY	S.B. Choi et al., <u>FLUID FLOW AND HEAT TRANSFER IN MICROTUBES</u> , 1991, DSC-vol. 32, Micromechanical sensors, Actuators, and Systems, ASME 1991, pages 123-134.
	DZ	S. F. Choquette, M. Faghri et al., <u>OPTIMUM DESIGN OF MICROCHANNEL HEAT SINKS</u> , 1996, DSC-Vol. 59, Microelectromechanical Systems (MEMS), ASME 1996, pages 115-126.
	EA	David Copeland et al., <u>MANIFOLD MICROCHANNEL HEAT SINKS: THEORY AND EXPERIMENT</u> , 1995, EEP-Vol. 10-2, Advances in Electronic Packaging ASME 1995, pages 829-835.
	EB	J. M. Cuta et al., <u>FORCED CONVECTION HEAT TRANSFER IN PARALLEL CHANNEL ARRAY MICROCHANNEL HEAT EXCHANGER</u> , 1996, PID-Vol. 27 HTD-Vol. 338, Advances in Energy efficiency, Heat/Mass Transfer Enhancement, ASME 1996, pages 17-23.
	EC	K. Fushinobu et al., <u>HEAT GENERATION AND TRANSPORT IN SUB-MICRON SEMICONDUCTOR DEVICES</u> , 1993, HTD-Vol. 253, Heat Transfer on the Microscale, ASME 1993, pages 21-28.
	ED	Charlotte Gillot et al., <u>Integrated Micro Heat Sink for Power Multichip Module</u> , September 3, 1999, IEEE Transactions on Industry Applications, Vol. 36, NO. 1, January/February 2000, pages 217-221.
	EE	John Gooding, <u>Microchannel heat exchangers - a review</u> , SPIE Vol. 1997 High Heat Flux Engineering II (1993), pages 66-82.
✓	EF	Koichiro Kawano et al., <u>Micro Channel Heat Exchanger for Cooling Electrical Equipment</u> , HTD-Vol. 361-3/PID-Vol. 3, Proceeding of the ASME Heat Transfer Division - Volume 3, ASME 1998, pages 173-188.
TM	EG	Chad Harris et al., <u>Design and Fabrication of a Cross Flow Micro Heat Exchanger</u> , December 2000, Journal of Microelectromechanical Systems, Vol. 9, No. 4, pages 502-508.

Examiner:

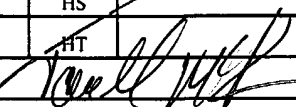
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TM	EH	George M. Harpole et al., <u>MICRO-CHANNEL HEAT EXCHANGER OPTIMIZATION</u> , 1991, Seventh IEEE SEMI-THERM Symposium, pages 59-63.					
	EI	Pei-Xue Jiang et al., <u>Thermal-hydraulic performance of small scale micro-channel and porous-media heat-exchangers</u> , 2001, International Journal of Heat and Mass Transfer 44 (2001), pages 1039-1051.					
	EJ	X.N. Jiang et al., <u>Laminar Flow Through Microchannels Used for Microscale Cooling Systems</u> , 1997, IEEE/CPMT Electronic Packaging Technology Conference, pages 119-122, Singapore.					
	EK	David Bazeley Tuckerman, <u>Heat-Transfer Microstructures for Integrated Circuits</u> , February 1984, pages ii-xix, pages 1-141.					
	EL	M Esashi, <u>Silicon micromachining for integrated microsystems</u> , 1996, Vacuum/volume 47/numbers 6-8/pages 469-474.					
	EM	T.S. Raviguruajan et al., <u>Effects of Heat Flux on Two-Phase Flow characteristics of Refrigerant Flows in a Micro-Channel Heat Exchanger</u> , HTD-Vol. 329, National Heat Transfer Conference, Volume 7, ASME 1996, pages 167-178.					
	EN	T.S. Raviguruajan et al., <u>Single-Phase Flow Thermal Performance Characteristics of a Parallel Micro-Channel Heat Exchanger</u> , 1996, HTD-Vol. 329, National Heat Transfer Conference, Volume 7, ASME 1996, pages 157-166					
	EO	T.S. Raviguruajan et al., <u>Liquid Flow Characteristics in a Diamond-Pattern Micro-Heat-Exchanger</u> , DSC-Vol. 59 Microelectromechanical Systems (MEMS), ASME 1996, pages 159-166					
	EP	T.S. Raviguruajan, <u>Impact of Channel Geometry on Two-Phase Flow Heat Transfer Characteristics of Refrigerants in Microchannel Heat Exchangers</u> , May 1998, Journal of Heat Transfer, Vol. 120, pages 485-491					
	EQ	J. Pfahler et al., <u>Liquid Transport in Micron and Submicron Channels</u> , March 1990, Sensors and Actuators, A21-A23 (1990), pages 431-434.					
	ER	Kenneth Pettigrew et al., <u>Performance of a MEMS based Micro Capillary Pumped Loop for Chip-Level Temperature Control</u> , 2001, The 14 th IEEE International Conference on Micro Electro Mechanical Systems, pages 427-430.					
	ES	C. Perret et al., <u>Microchannel integrated heat sinks in silicon technology</u> , October 12-15, 1998, The 1998 IEEE Industry Applications Conference, pages 1051-1055.					
	ET	X.F. Peng et al., <u>Convective heat transfer and flow friction for water flow in microchannel structures</u> , 1996, Int. J. Heat Mass Transfer, Vol. 39, No. 12, pages 2599-2608, printed in Great Britain.					
	EU	X.F. Peng et al., <u>Experimental investigation of heat transfer in flat plates with rectangular microchannels</u> , 1994, Int. J. Heat Mass Transfer, Vol. 38, No. 1, pages 127-137, printed in Great Britain.					
	EV	X.F. Peng et al., <u>Cooling Characteristics with Microchanneled Structures</u> , 1994, Enhanced Heat Transfer, Vol. 1, No. 4, pages 315-326, printed in the United States of America.					
	EW	Yoichi Murakami et al., <u>Parametric Optimization of Multichanneled Heat Sinks for VLSI Chip Cooling</u> , March 2002, IEEE Transaction on Components and Packaging Technologies, Vol. 24, No. 1, pages 2-9.					
	EX	D. Mundinger et al., <u>High average power 2-D laser diode arrays or silicon microchannel coolers</u> , CLEO '89/Friday Morning/404.					
	EY	L.J. Missaggia et al., <u>Microchannel Heat Sinks for Two-Dimensional High-Power-Density Diode Laser Arrays</u> , 1989, IEEE Journal of Quantum Electronics, Vol. 25, No. 9, September 1989, pages 1989-1992.					
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	FA	C.R. Friedrich et al., <u>Micro heat exchangers fabricated by diamond machining</u> , January 1994, Precision Engineering, Vol. 16, No. 1, pages 56-59					
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Examiner: <i>Mei W. H.</i>				Date Considered: <i>8-2-04</i>			
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Thomas W. Kenny et al.	
				Filing Date: August 18, 2003	Group Art Unit: 1763
(37 CFR § 1.98(b))					
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Examiner: <i>Paul M. [Signature]</i>		Date Considered: <i>8-2-04</i>			
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Thomas W. Kenny et al.	
(37 CFR § 1.98(b))				Filing Date: August 18, 2003	Group Art Unit: 1763
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)					
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Examiner: 		Date Considered: 8-2-04			
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
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Title of Invention 	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE
Application Number:	10/643684
Confirmation Number:	4600
First Named Applicant:	Thomas Kenny
Attorney Docket Number:	
Search string:	(6090251 or 6096656 or 6100541 or 6101715 or 6119729 or 6126723 or 6129145 or 6129260 or 6131650 or 6146103 or 6154363 or 6159353 or 6171067 or 6174675 or 6176962 or 6186660 or 6210986 or 6216343 or 6221226 or 6227809 or 6234240 or 6238538 or 6277257 or 6287440 or 6301109 or 6313992 or 6317326 or 6321791 or 6322753 or 6324058 or 6337794 or 6351384 or 6388317 or 6396706 or 6400012 or 6406605 or 6415860 or 6416642 or 6417060 or 6424531 or 6443222 or 6444461 or 6457515 or 6495015 or 6537437 or 6543521 or 6553253 or 6572749 or 6588498 or 6591625).pn.

10/643684

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Examiner Name	Date

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8
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Title of Invention	APPARATUS AND METHOD OF FORMING CHANNELS IN A HEAT-EXCHANGING DEVICE	
Application Number:	10/643684	*10/643684*
Confirmation Number:	4600	
First Named Applicant:	Thomas Kenny	
Attorney Docket Number:		
Search string:	(5383340 or 5421943 or 5427174 or 5436793 or 5459099 or 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618 or 5759014 or 5763951 or 5774779 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5869004 or 5870823 or 5874795 or 5876655 or 5880017 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164 or 6019882 or 6054034 or 6068752).pn.	

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date

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Title of
Invention APPARATUS AND METHOD OF FORMING CHANNELS IN
A HEAT-EXCHANGING DEVICE

Application Number: 10/643684 *10/643684*
Confirmation Number: 4600
First Named Applicant: Thomas Kenny
Attorney Docket Number:
Search string: (3654988 or 3817321 or 3823572 or 3923426
or 3929154 or 4109707 or 4138996 or
4194559 or 4248295 or 4312012 or 4450472
or 4485429 or 4516632 or 4540115 or
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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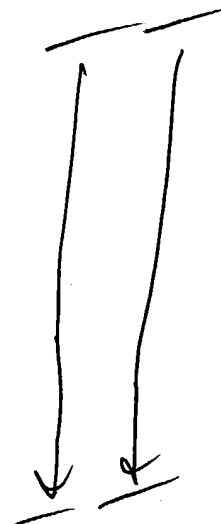
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Signature

Signature Name _____ Date _____

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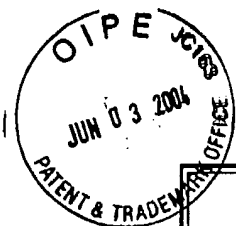
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Signature

Examiner Name	Date
<i>Scott M. Henderson</i>	8-2-04



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
Invention

APPARATUS AND METHOD OF FORMING CHANNELS IN
A HEAT-EXCHANGING DEVICE

Application Number: 10/643684



Confirmation Number: 4600

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Search string: (4467861 or 4903761 or 5016090 or 5269372
or 5275237 or 5310440 or 5346000 or 5388635
or 5945217 or 6019165 or 6034872 or 6039114
or 6253832 or 6257320 or 6330907 or 6336497
or 6366462 or 6367544 or 6431260 or 6466442
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or 6609560 or 6651735 or 20030213580).pn.

US Patent Documents


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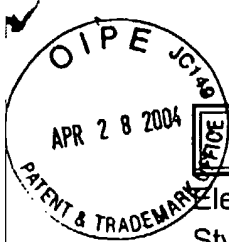
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<p>Application Number: 10/643684 </p> <p>Confirmation Number: 4600</p> <p>First Named Applicant: Thomas Kenny</p> <p>Attorney Docket Number:</p> <p>Search string: (3948316 or 5161089 or 5228502 or 5239443 or 5265670 or 5978220 or 5993750 or 6729383).pn.</p> <p><u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><i>TM</i></td><td>1</td><td>3948316</td><td>1976-04-06</td><td>Souriau</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>2</td><td>5161089</td><td>1992-11-03</td><td>Chu et al.</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>3</td><td>5228502</td><td>1993-07-20</td><td>Chu et al.</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>4</td><td>5239443</td><td>1993-08-24</td><td>Fahey et al.</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>5</td><td>5265670</td><td>1993-11-30</td><td>Zingher</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>6</td><td>5978220</td><td>1999-11-02</td><td>Frey et al.</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>7</td><td>5993750</td><td>1999-11-30</td><td>Ghosh et al.</td><td></td><td></td><td></td></tr><tr><td><i>TM</i></td><td>8</td><td>6729383</td><td>2004-05-04</td><td>Cannell et al.</td><td>B1</td><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	<i>TM</i>	1	3948316	1976-04-06	Souriau				<i>TM</i>	2	5161089	1992-11-03	Chu et al.				<i>TM</i>	3	5228502	1993-07-20	Chu et al.				<i>TM</i>	4	5239443	1993-08-24	Fahey et al.				<i>TM</i>	5	5265670	1993-11-30	Zingher				<i>TM</i>	6	5978220	1999-11-02	Frey et al.				<i>TM</i>	7	5993750	1999-11-30	Ghosh et al.				<i>TM</i>	8	6729383	2004-05-04	Cannell et al.	B1		
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Signature

8-2-04